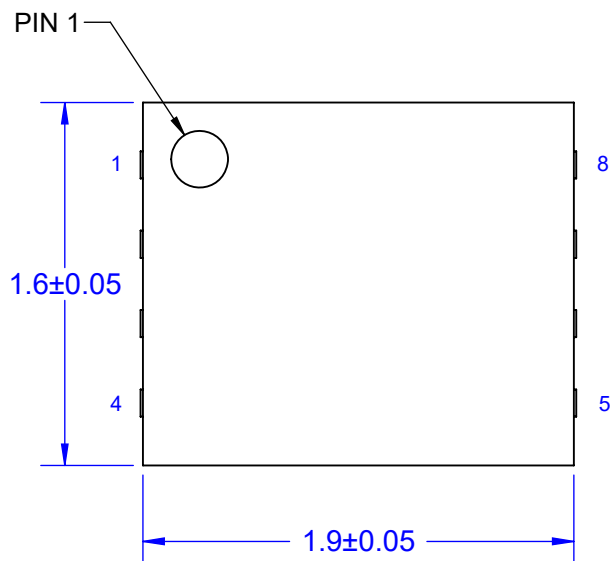
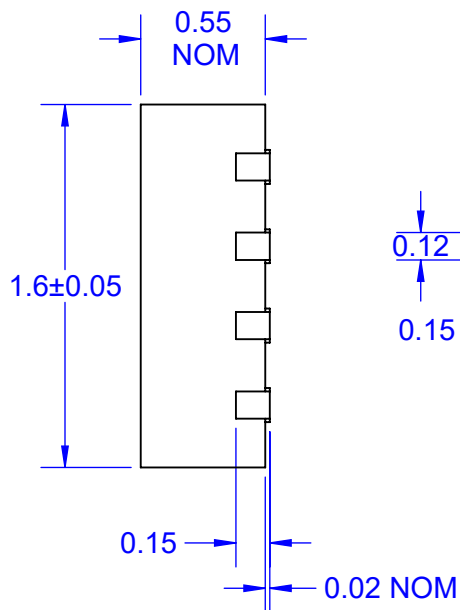


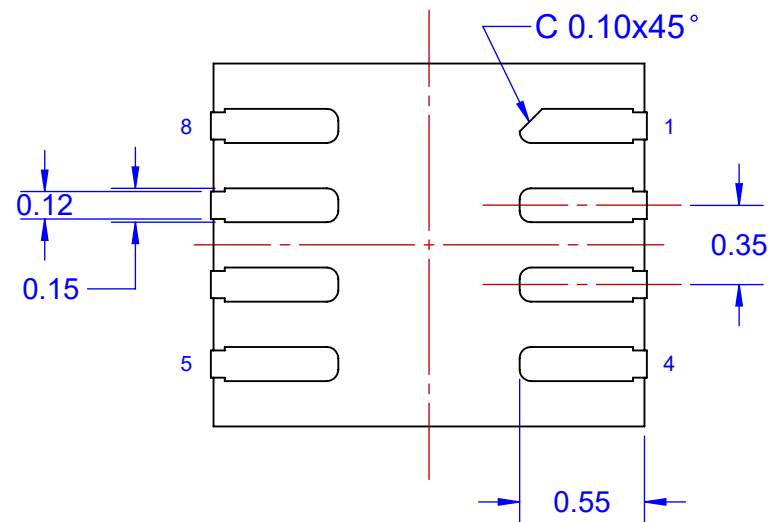
TOP VIEW



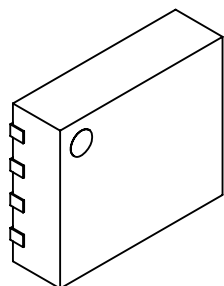
SIDE VIEW



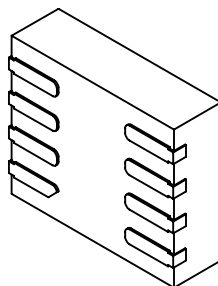
BOTTOM VIEW



MODEL



TOP



BOTTOM

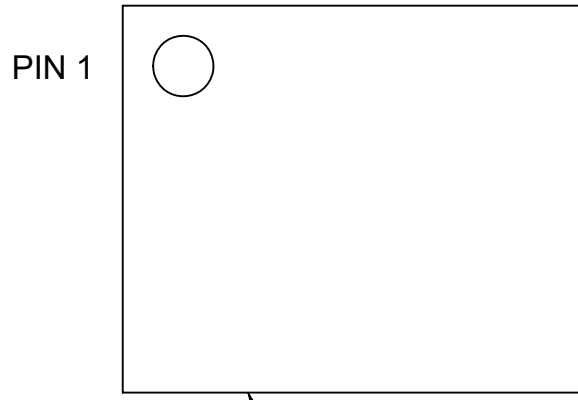
Notes: (Unless Otherwise Specified).

- 1) BODY: PLASTIC, SEMICONDUCTOR GRADE.
- 2) LEAD FRAME: COPPER, C-194 F/H.
- 3) LEAD FRAME PLATING: Sn100.
- 4) FRAME THICKNESS: 0.15mm.
- 5) DIE PAD: NOT EXPOSED.
- 6) JEDEC OUTLINE: MO-220.
- 7) DIMENSIONS IN mm.

APPROVALS	DATE	TopLine®			
DRAWN T. Au	7/13/2023				
ENG M. Hart	7/13/2023	TITLE 8-LEAD 1.6x1.9mm P=0.35mm DFN DAISY CHAIN			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		15:1	A	430840	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 5
REVISED					

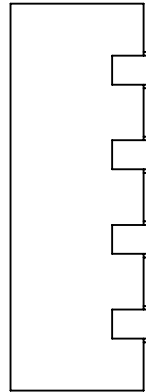
DAISY CHAIN PATTERN

TOP VIEW

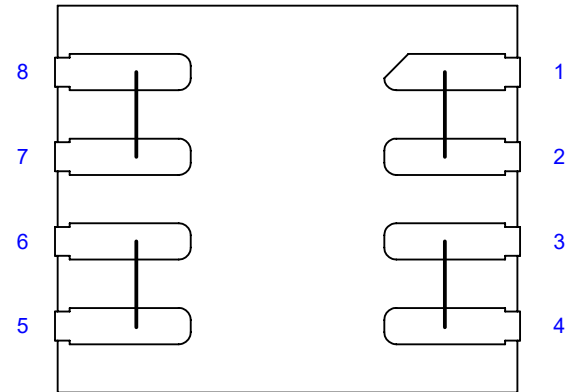


TOP SIDE ENCAPSULATION

SIDE VIEW



BOTTOM VIEW



NOTE:
1. PACKAGE DAISY CHAIN BY WIRE BONDING TO INTERNAL BOND PADS.

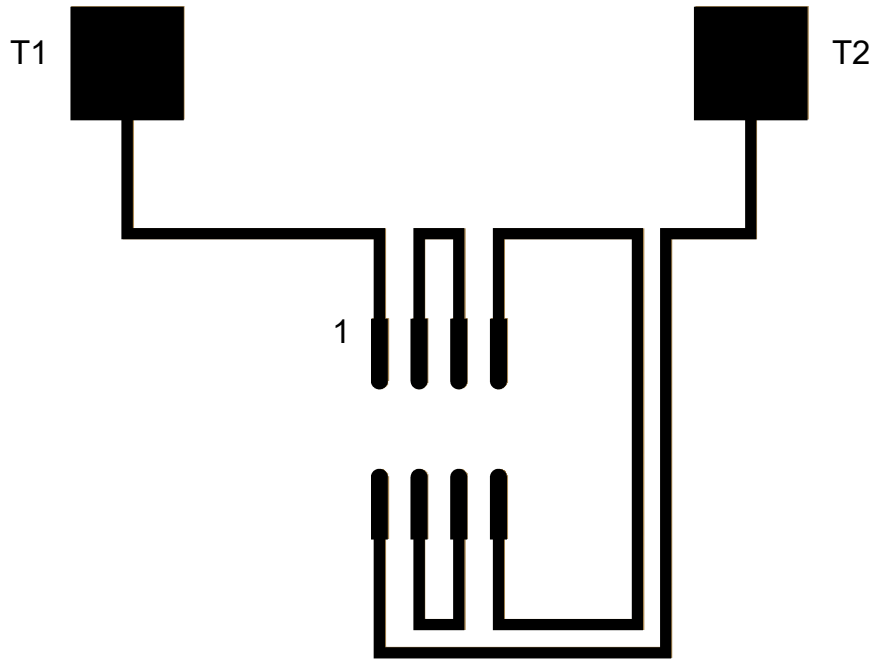
TopLine[®]

TITLE 8-LEAD 1.6x1.9mm P=0.35mm
DFN DAISY CHAIN

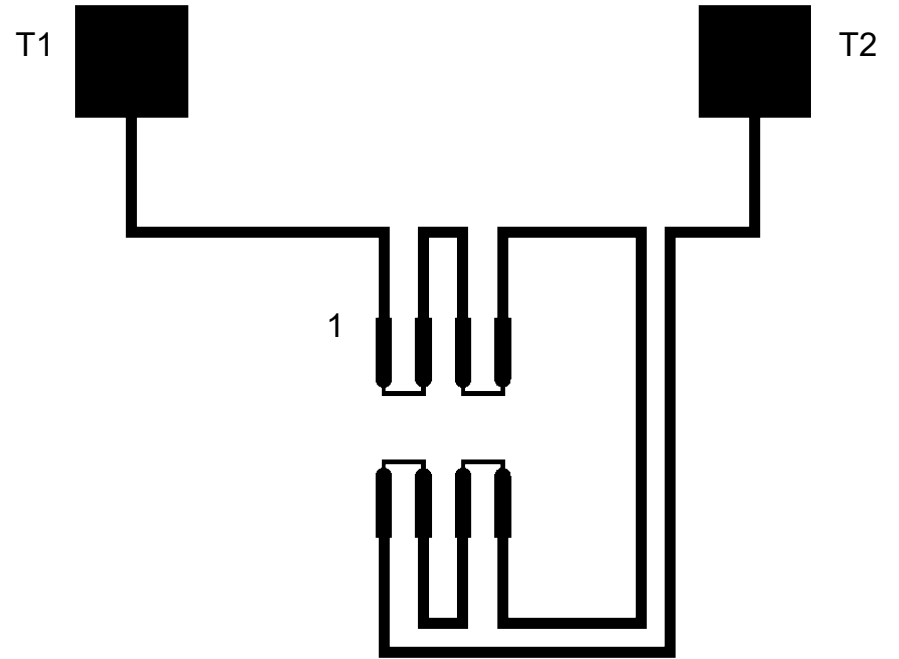
SCALE 16:1	SIZE A	DRAWING NO. 430840	REV A
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DO NOT SCALE DRAWING

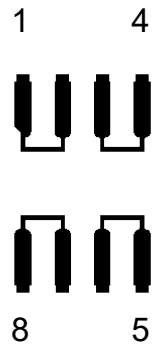
SHEET 2 OF 5



RECOMMENDED
PCB PADS




AFTER MOUNTING
ON PCB

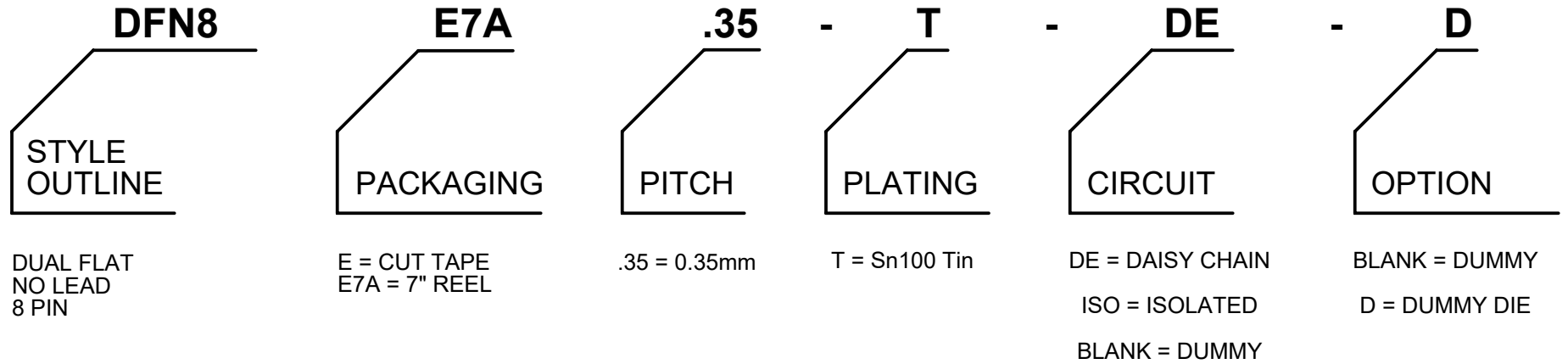


DFN

DAISY CHAIN NET LIST	
PINS	PINS
1 ~ 2	3 ~ 4
5 ~ 6	7 ~ 8

			
TITLE 8-LEAD 1.6x1.9mm P=0.35mm DFN DAISY CHAIN			
SCALE 10:1	SIZE A	DRAWING NO. 430840	REV A
DO NOT SCALE DRAWING			SHEET 3 OF 5

PART NUMBERING SYSTEM

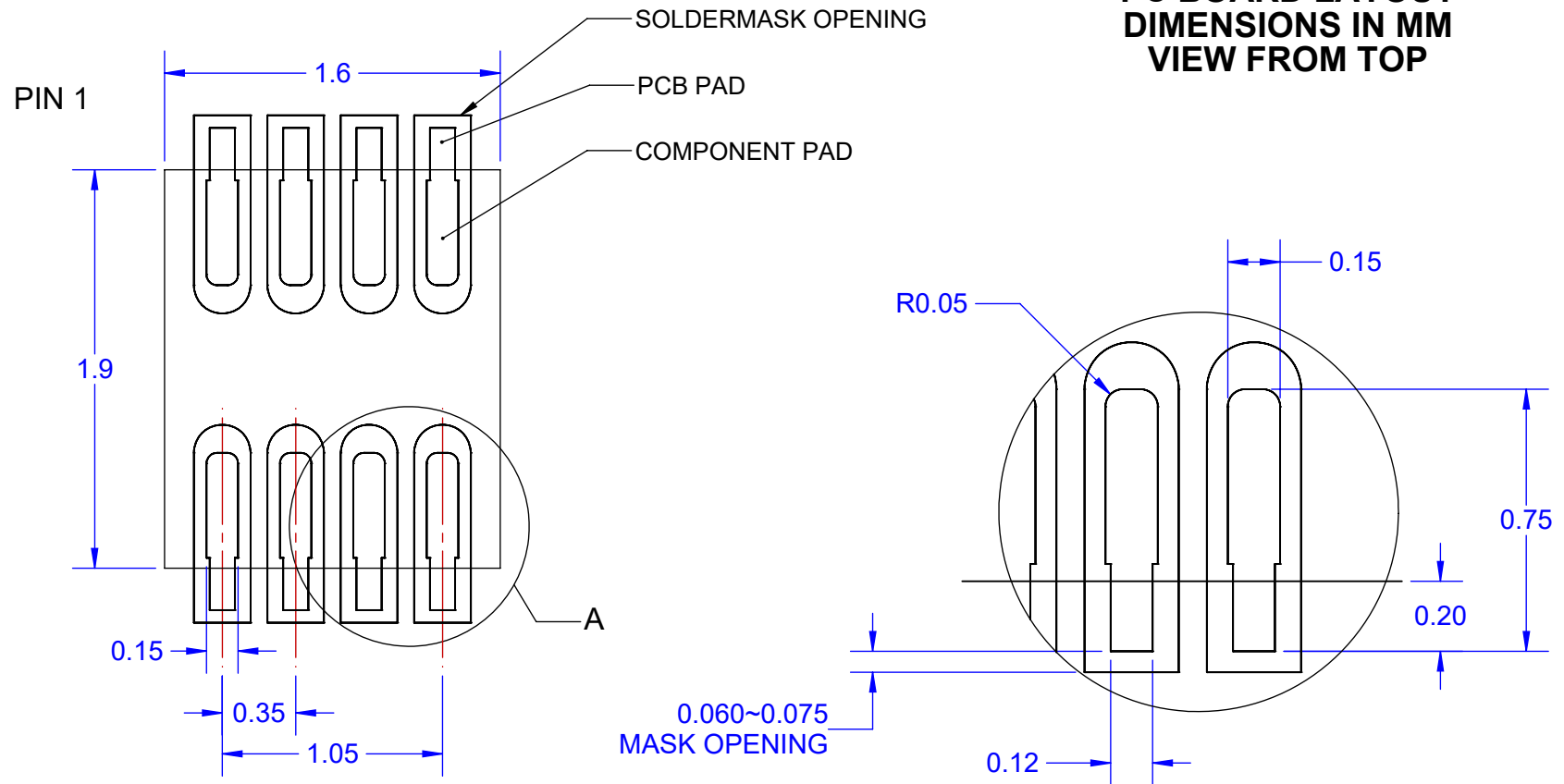


PART NUMBER	DAISY CHAIN	PACKAGING	RoHS Pb-FREE	DUMMY DIE
DFN8E7A.35-T-DE-D	YES	REEL	YES	YES
DFN8E.35-T-DE-D	YES	CUT TAPE	YES	YES

OTHER PART NUMBER COMBINATIONS AVAILABLE. CONTACT TOPLINE.

TopLine®			
TITLE 8-LEAD 1.6x1.9mm P=0.35mm DFN DAISY CHAIN			
SCALE NONE	SIZE A	DRAWING NO. 430840	REV A
DO NOT SCALE DRAWING			SHEET 4 OF 5

PC BOARD LAYOUT DIMENSIONS IN MM VIEW FROM TOP



DETAIL A
SCALE 50 : 1

Notes: (Unless Otherwise Specified).

- 1) DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE BASE WHEN DESIGNING THE PCB.
- 2) SURROUND EACH SIDE OF I/O PERIMETER PADS WITH 0.060~0.075 mm (NSMD) SOLDER MASK OPENING (2.4~3.0mils) OPTIONALLY OK TO USE RECTANGLE (NSMD) MASK OPENING AROUND I/O PADS.
- 3) ROUNDED PCB LAND PADS REDUCE SOLDER BRIDGING. PAD CHAMFER ANGLE MAY VARY.
- 4) PCB LANDS SHOULD BE 0.2mm LONGER THAN THE PACKAGE I/O PADS.
- 5) THE WIDTH OF PERIMETER PCB PADS SHOULD MATCH (1:1) THE WIDTH OF THE PACKAGE PADS.
- 6) REFER TO INDUSTRY REFERENCES SUCH AS IPC-SM-782 FOR PCB LAND PATTERN DESIGN.
- 7) THERMAL GROUND PADS MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
 - A) MAKE COPPER THERMAL PAD AS LARGE AS POSSIBLE.
 - B) DRILL MULTIPLE THERMAL VIAS 0.25~0.33mm DIAMETER USING 0.8~1.2mm PITCH GRID.
 - C) PLATE THERMAL VIA BARRELS WITH 1-OUNCE COPPER (18 μ m).
 - D) TENT (COVER) THERMAL VIAS WITH SOLDER MASK 0.1mm LARGER THAN THE VIA DIAMETER.
- 8) STENCIL DESIGN MAY BE CHANGED TO SUIT REQUIREMENTS OF THE DESIGNER.
 - A) LASER CUT STENCIL 0.125mm (5mil) THICK. APERTURE SIZE-TO-LAND RATIO OF 1:1.
 - B) THE SOLDER PASTE OPENING IN THE THERMAL PAD AREA SHOULD BE A MATRIX ARRAY OF SMALLER APERTURES INSTEAD OF ONE LARGE APERTURE TO CONTROL PASTE AMOUNTS.
 - C) APPLY 50% TO 80% SOLDER PASTE COVERAGE IN THE PAD AREA.

TopLine[®]

TITLE 8-LEAD 1.6x1.9mm P=0.35mm
DFN DAISY CHAIN

SCALE	SIZE	DRAWING NO.	REV
18:1	A	430840	A

DO NOT SCALE DRAWING

SHEET 5 OF 5